

Applications

- For GPS applications

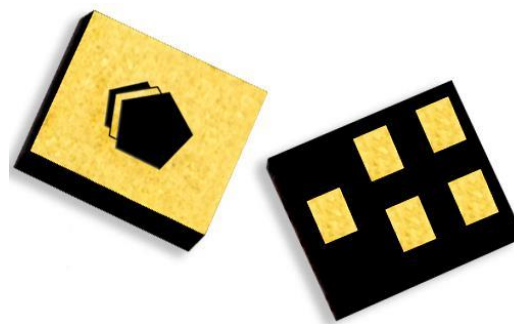
Product Features

- Ultra-Low Loss
- Usable bandwidth 20.46 MHz
- Single-ended operation
- Ceramic chip-scale Package (CSP)
- Small Size: 1.40 x 1.20 x 0.46 mm
- Hermetically Sealed
- **RoHS** compliant, **Pb**-free

General Description

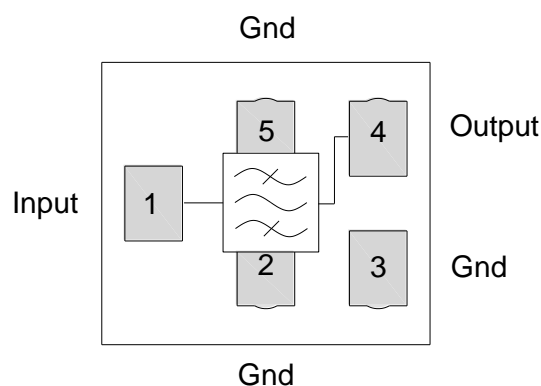
857139 is specifically designed for GPS applications.

857139 uses advanced and inexpensive packaging techniques to achieve an extremely small 1.40 x 1.20 x 0.46 mm hermetically sealed package.



Functional Block Diagram

Top view



Pin Configuration

Pin #	Balanced	Description
1		Input
4		Output
2,3,5		Ground

Ordering Information

Part No.	Description
857139	packaged part
857139-EVB	evaluation board

Standard T/R size = 10000 units/reel.

Absolute Maximum Ratings

Parameter	Rating
Operating Temperature	-55 to + 85 °C
Storage Temperature ⁽¹⁾	-55 to + 85 °C
RF Input Power ⁽²⁾	+20 dBm

Notes:

1. Device may operate over this range with degraded Electrical Specifications.
2. Device is measured for equivalent 10K hours @ + 85 °C [CW Signal]

Operation of this device outside the parameter ranges given above may cause permanent damage.

Electrical Specifications ⁽¹⁾

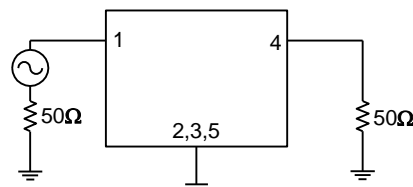
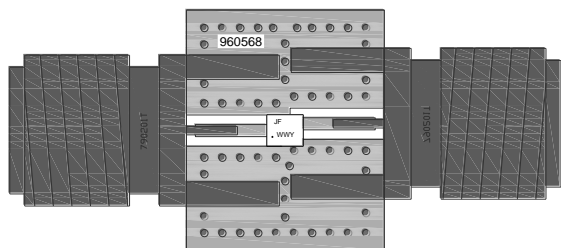
Test conditions unless otherwise noted: ⁽²⁾ -55 °C to +85 °C

Parameter ⁽³⁾	Conditions	Min	Typical ⁽⁴⁾	Max	Units
Center Frequency		-	1575.42	-	MHz
Maximum Insertion Loss	1574.22 – 1576.62 MHz	-	0.6	0.9	dB
Lower 2.0dB Bandedge		-	1554.25	1565.19	MHZ
Upper 2.0dB Bandedge		1585.65	1600.91	-	MHZ
Lower 21dB Bandedge		1525.42	1532.69	-	MHZ
Upper 21dB Bandedge		-	1617.78	1625.42	MHZ
Amplitude Variation	1574.22 – 1576.62 MHz	-	0.02	0.2	dB p-p
Relative Attenuation ⁽⁵⁾	824 – 960 MHz	20	22.5	-	dB
	1500 – 1525.42 MHz	21	29.6	-	dB
	1625.42 – 1650 MHz	21	32.6	-	dB
	1710 – 2170 MHz	20	21.8	-	dB
Input Return Loss	1574.22 – 1576.62 MHz	15	28.6	-	dB
Output Return Loss	1574.22 – 1576.62 MHz	15	29.2	-	dB
Source Impedance (Single-ended) ⁽⁶⁾		-	50	-	Ω
Load Impedance (Single-ended) ⁽⁶⁾		-	50	-	Ω

Notes:

1. All specifications are based on the TriQuint schematic shown on page 3.
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature.
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances.
4. Typical values are based on average measurements at room temperature.
5. Relative to zero dB.
6. This is the optimum impedance in order to achieve the performance shown.

Evaluation Board



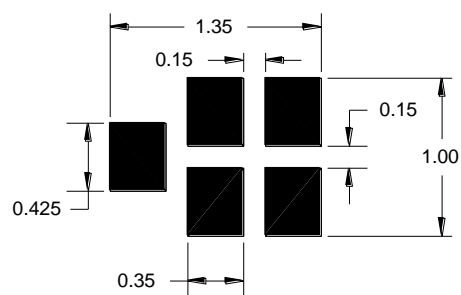
Notes:

Top, middle & bottom layers: 1 oz copper
Substrates: FR4 dielectric, .031" thick
Finish plating: Nickel: 3-8 μ m thick, Gold: .03-.2 μ m thick
Hole plating: Copper min .0008 μ m thick

Bill of Material

Reference Des.	Value	Description	Manuf.	Part Number
U1	N/A	1575.42 MHz SAW Filter	TriQuint	857139
SMA	N/A	SMA connector	Radiall	9602-1111-018
PCB	N/A	3 Layer	Multiple	960568

PCB Mounting Pattern

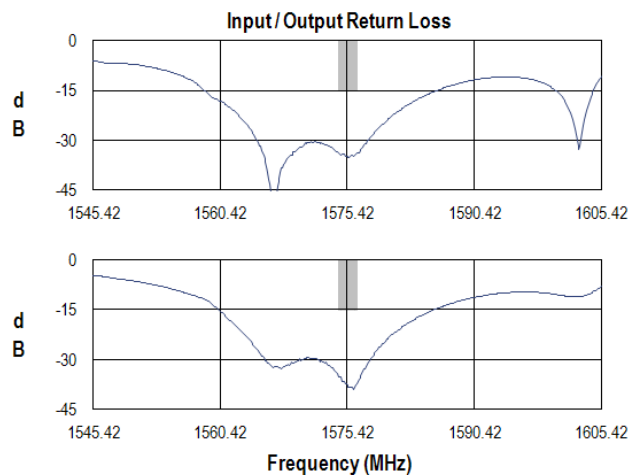
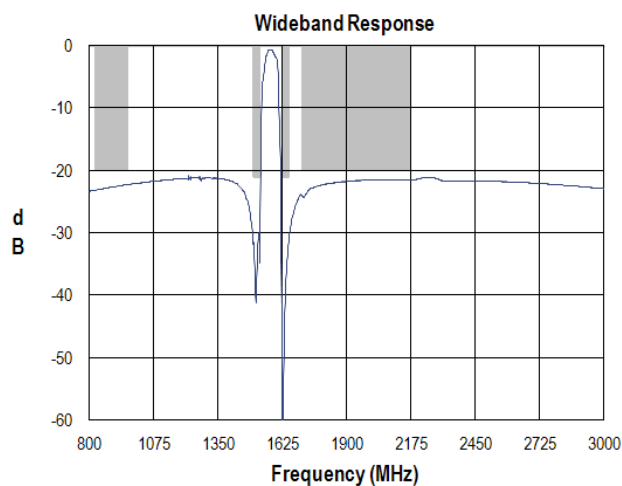
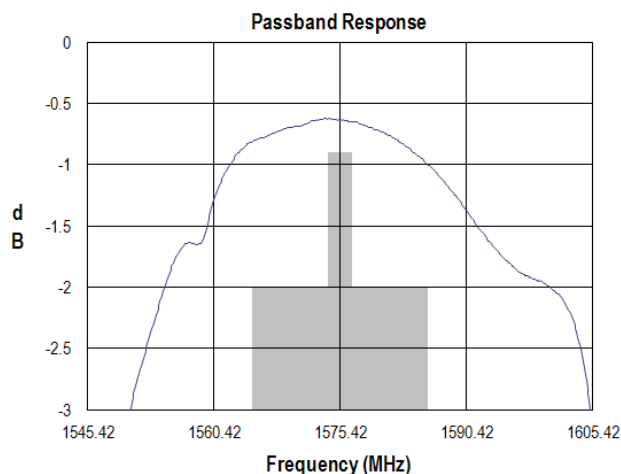
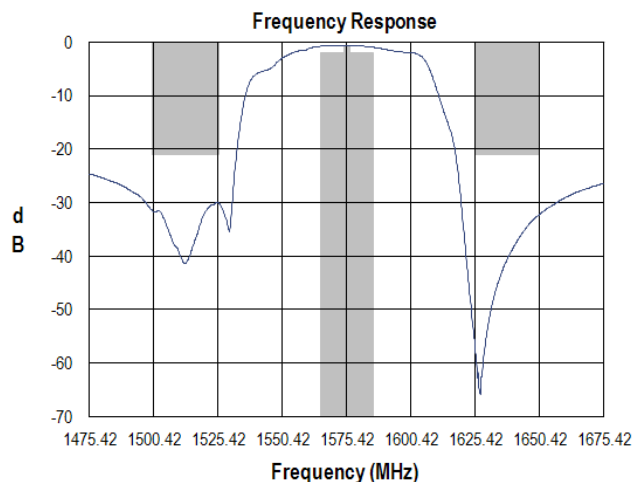


Notes:

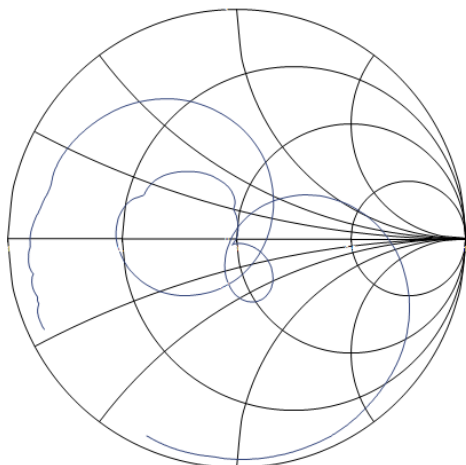
1. All dimensions are in millimeters.
2. This footprint represents a recommendation only.

Performance Plots

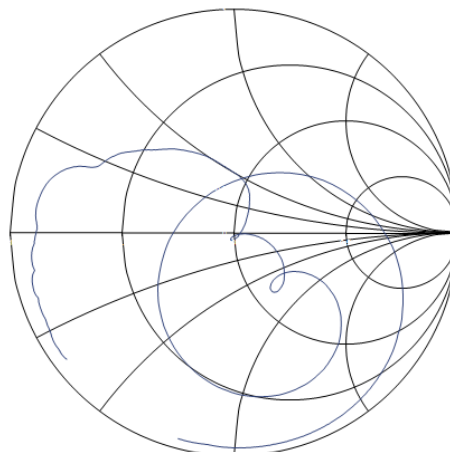
Test conditions unless otherwise noted: Temp= +25 °C



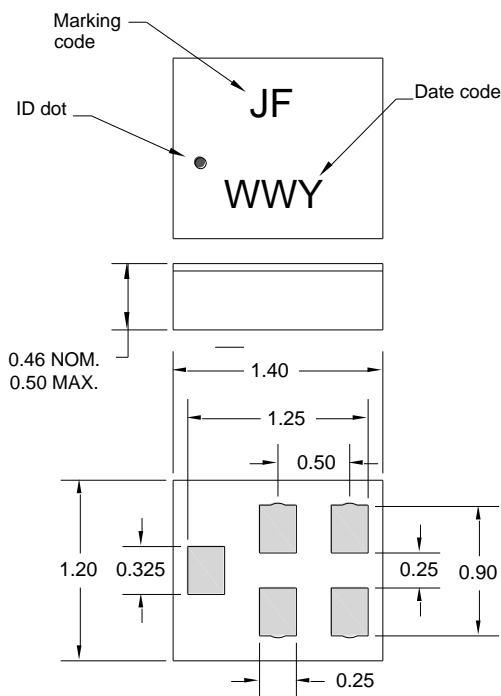
Input Smith Chart



Output Smith Chart



Package Information, Marking and Dimensions



Package Style: CSP-5BT
Dimensions: 1.40 x 1.20 x 0.46 mm

Body: Al_2O_3 ceramic
Lid: Kovar or Alloy 42, Au over Ni plated
Terminations: Au plating 0.5 - 1.0 μ m, over a 2-6 μ m Ni plating

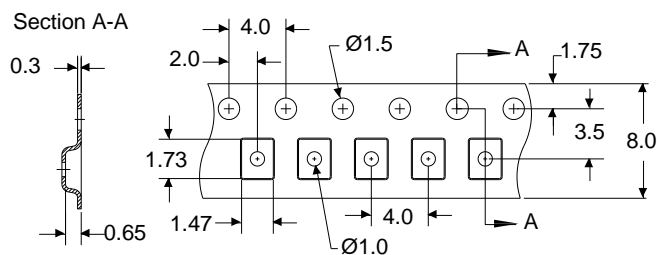
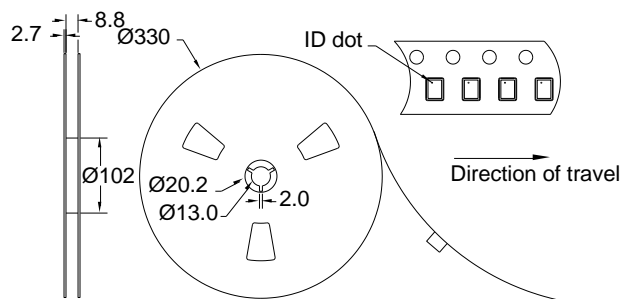
The date code consists of: WW = 2 digit week and Y = last digit of year

Notes:

1. All dimensions shown are Typical in millimeters
2. All tolerances are ± 0.05 mm except overall length and width ± 0.10 mm.
3. An asterisk (*) in front of the marking code indicates prototype.

Tape and Reel information

Standard T/R size = 10,000 units/reel. All dimensions are in millimeters



Product Compliance Information

ESD Information



Caution! ESD-Sensitive Device

ESD Rating: Class 1A
Test: Human Body Model (HBM)
Standard: ESDA/JEDEC JS-001

MSL Rating

Devices are hermetic, therefore MSL is not applicable.

Solderability

Compatible with the latest version of J-STD-020, lead free solder, 260°C

Refer to [Soldering Profile](#) for recommended guidelines.

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

Halogen Free (Chlorine, Bromine)

Antimony Free

TBBP-A (C₁₅H₁₂Br₄O₂) Free

PFOS Free

SVHC Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Web: www.triquint.com

Tel: 877-800-8584

Email: customer.support@qorvo.com

For information about the merger of RFMD and TriQuint as Qorvo:

Web: www.qorvo.com

For technical questions and application information:

Email: flapplication.engineering@tqs.com

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